

# NXP NX5P2090 power switch datasheet

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The NX5P2090 is an advanced power switch for USB OTG applications. It includes under-voltage and over-voltage lockout, over-current, over-temperature, reverse bias and in-rush current protection circuits. These are designed to automatically isolate a VBUS OTG voltage source from a VBUS interface pin when a fault occurs. The device features two power switch terminals, one input (VINT) and one output (VBUS); a current limit input (ILIM) for defining the over-current and in-rush current limit; a voltage detect output (VDET) to monitor the voltage level on VBUS; an open-drain fault output (FAULT) to indicate when a fault condition has occurred and an enable input (EN) to control the state of the switch. When EN is set LOW the device enters a low-power mode, disabling all protection circuits except the under-voltage lockout. The low-power mode can be entered at anytime unless the over temperature protection circuit has been triggered.

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# NX5P2090

## Logic controlled high-side power switch

Rev. 2 — 12 December 2013

Product data sheet

## 1. General description

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The NX5P2090 is an advanced power switch for USB OTG applications. It includes under-voltage and over-voltage lockout, over-current, over-temperature, reverse bias and in-rush current protection circuits. These are designed to automatically isolate a VBUS OTG voltage source from a VBUS interface pin when a fault occurs. The device features two power switch terminals, one input (VINT) and one output (VBUS); a current limit input (ILIM) for defining the over-current and in-rush current limit; a voltage detect output (VDET) to monitor the voltage level on VBUS; an open-drain fault output (FAULT) to indicate when a fault condition has occurred and an enable input (EN) to control the state of the switch. When EN is set LOW the device enters a low-power mode, disabling all protection circuits except the under-voltage lockout. The low-power mode can be entered at anytime unless the over temperature protection circuit has been triggered.

Designed for operation from 3 V to 5.5 V, it is used in power domain isolation applications to protect from out of range operation. The enable input includes integrated logic level translation making the device compatible with lower voltage processors and controllers.

## 2. Features and benefits

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- Wide supply voltage range from 3 V to 5.5 V
- 30 V tolerant on VBUS
- $I_{SW}$  maximum 2 A continuous current
- Very low ON resistance: 100 m $\Omega$  (maximum) at a supply voltage of 4.0 V
- Low-power mode (ground current 20  $\mu$ A typical)
- 1.8 V control logic
- Soft start turn-on slew rate
- Protection circuitry
  - ◆ Over-temperature protection
  - ◆ Over-current protection with low current output mode
  - ◆ Reverse bias current/Back drive protection
  - ◆ Over-voltage lockout
  - ◆ Under-voltage lockout
  - ◆ Analog voltage limited VBUS monitor path
- ESD protection:
  - ◆ HBM ANSI/ESDA/JEDEC JS-001 Class 2 exceeds 2 kV
  - ◆ IEC61000-4-2 contact discharge exceeds 8 kV for pins VBUS
- Specified from  $-40$  °C to  $+85$  °C



### 3. Applications

- USB OTG applications

### 4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
NX5P2090UK	-40 °C to +85 °C	WLCSP9	wafer level chip-scale package; 9 bumps; body 1.36 x 1.36 x 0.51 mm. (Backside Coating included)	NX5P2090UK

### 5. Marking

Table 2. Marking codes

Type number	Marking code
NX5P2090UK	NX5P2

### 6. Functional diagram

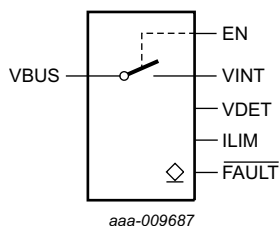


Fig 1. Logic symbol

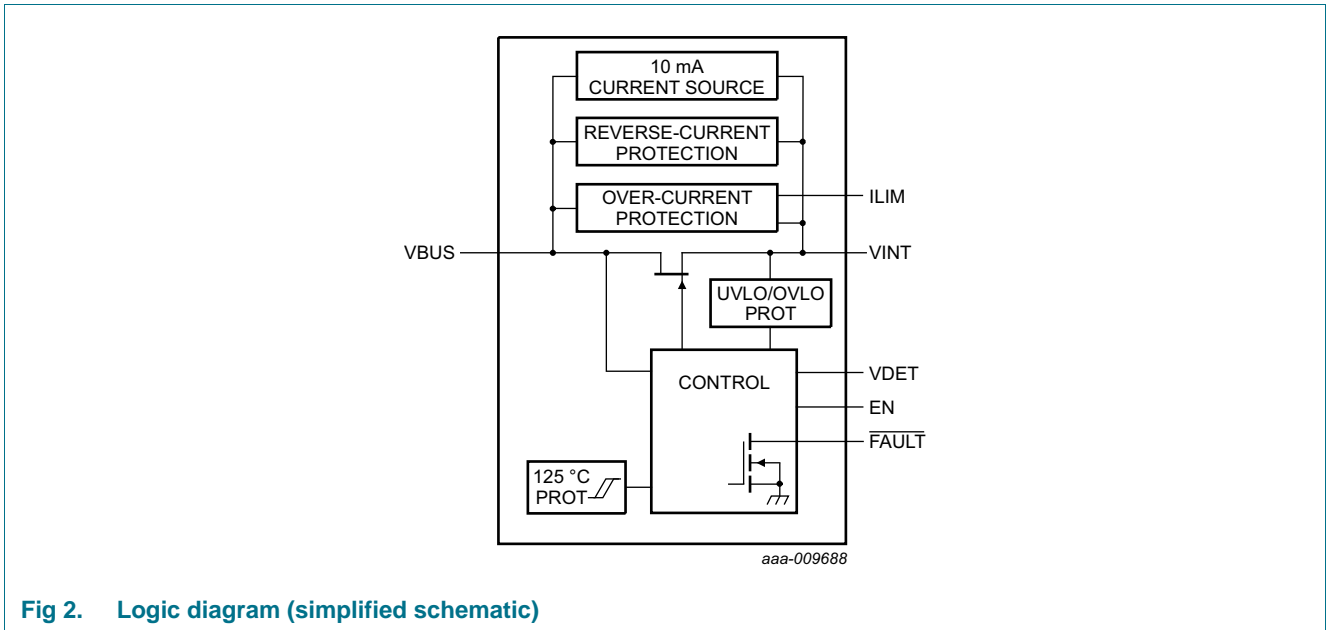


Fig 2. Logic diagram (simplified schematic)

## 7. Pinning information

### 7.1 Pinning

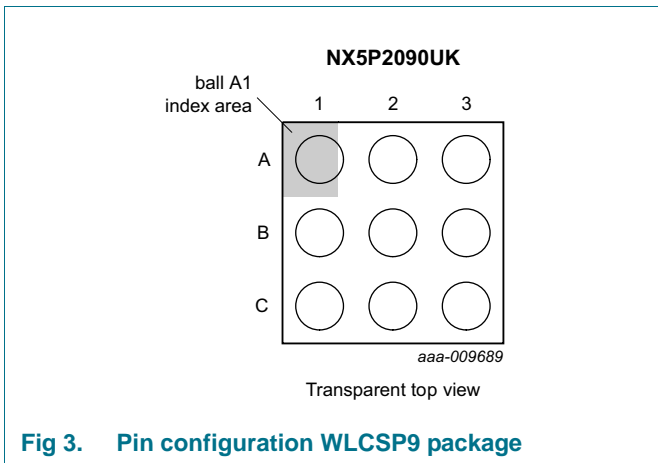


Fig 3. Pin configuration WLCSP9 package

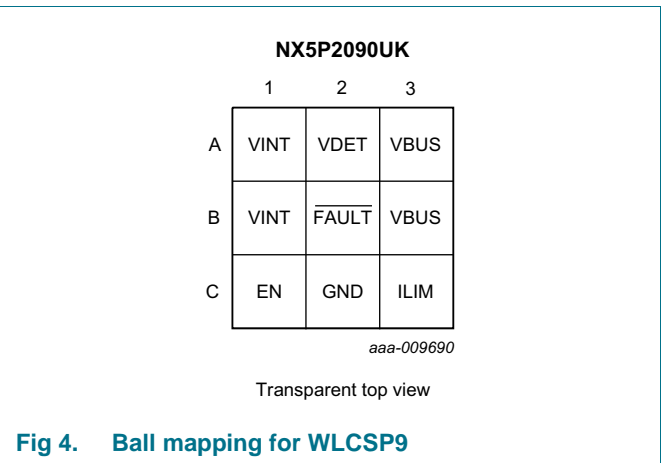


Fig 4. Ball mapping for WLCSP9

## 7.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
VINT	A1, B1	internal circuitry voltage I
VBUS	A3, B3	external connector voltage O
EN	C1	enable input (active HIGH) I
ILIM	C3	current limiter I/O
VDET	A2	VBUS voltage level indicator O
FAULT	B2	fault condition indicator (open-drain; active LOW)
GND	C2	ground (0 V)

## 8. Functional description

Table 4. Function table<sup>[1]</sup>

EN	VINT	VBUS	FAULT	Operation mode
X	0 V	Z	L	No supply
X	0 V	< 30 V	Z	Disabled; switch open
X	< 3.2 V	Z	L	Under-voltage lockout; switch open
H	> 5.5 V	Z	L	Over-voltage lockout; switch open
H	3.2 V to 5.5 V	Z	L	Over-temperature; switch open
L	3.2 V to 5.5 V	Z	Z	Disabled; switch open
H	3.2 V to 5.5 V	VBUS = VINT	Z	Enabled; switch closed; active
H	3.2 V to 5.5 V	0 V to VINT	L	Over-current; Switch open; constant current on VBUS
H	3.2 V to 5.5 V	0 V to VINT	L	When ILIM is connected to GND, VBUS is default supplied with 10 mA current source
H	3.2 V to 5.5 V	$VINT + 30 \text{ mV} < VBUS < VINT + 0.45 \text{ V} (> 4 \text{ ms})$	L	Reverse bias current/back drive; switch open
H	3.2 V to 5.5 V	$VBUS > VINT + 0.7 \text{ V}$	L	Reverse bias current/back drive; switch open

[1] H = HIGH voltage level; L = LOW voltage level, Z = high-impedance OFF-state, X = Don't care.

Table 5. Function table VDET versus VBUS<sup>[1]</sup>

VBUS	VDET	Operation mode
$3 \text{ V} < VBUS < 30 \text{ V}$	$1.5 < VDET < 5.5 \text{ V}$	VDET detects VBUS voltage

[1] See [Figure 22](#).

### 8.1 EN input

If EN is set LOW, the N-channel MOSFET is disabled, the  $\overline{\text{FAULT}}$  output is set HIGH-impedance and the device enters low-power mode. In low-power mode, all protection circuits are disabled except the under-voltage lockout circuit. If EN is set HIGH, all protection circuits are reactivated. If no fault conditions exist and an  $R_{\text{ILIM}}$  current limit resistor is detected, the N-channel MOSFET is enabled.

### 8.2 Under-voltage lockout (UVLO)

The UVLO circuit is active until  $V_{\text{INT}} > 3.2$  V. It disables the N-channel MOSFET, sets the  $\overline{\text{FAULT}}$  output LOW and returns the device to low-power mode. This occurs independently of the logic level on the EN pin. Once  $V_{\text{INT}} > 3.2$  V, the EN pin controls the N-channel MOSFET state. The UVLO circuit remains active in low-power mode.

### 8.3 Over-voltage lockout (OVLO)

If EN is set HIGH and  $V_{\text{INT}} > 5.75$  V, the OVLO circuit is active. It disables the N-channel MOSFET and sets the  $\overline{\text{FAULT}}$  output LOW. In low-power mode, the OVLO circuit is disabled and does not change the  $\overline{\text{FAULT}}$  output state. If the OVLO circuit is active, setting the EN pin LOW returns the device to low-power mode.

### 8.4 ILIM

The over-current protection circuit's (OCP) trigger value  $I_{\text{ocp}}$ , is set using an external resistor connected to the ILIM pin (see [Figure 6](#)). If EN is set HIGH and the ILIM pin is grounded, the device is in over-current. The N-channel MOSFET is disabled, the  $\overline{\text{FAULT}}$  output is set LOW and VBUS supplied by the 10 mA current source.

### 8.5 Over-current protection (OCP)

When the current through the N-channel MOSFET exceeds  $I_{\text{ocp}}$  for 20  $\mu\text{s}$  or  $V_{\text{BUS}} < V_{\text{INT}} - 200$  mV, the device is in over-current. The OCP circuit disables the N-channel MOSFET within 2  $\mu\text{s}$ , sets the  $\overline{\text{FAULT}}$  output LOW and supplies VBUS from the 10 mA current source. The OCP circuit is automatically reset when  $V_{\text{INT}} > V_{\text{BUS}} > V_{\text{INT}} - 200$  mV for 20  $\mu\text{s}$ . The N-channel MOSFET assumes the state defined by EN, the 10 mA current source is disconnected and the  $\overline{\text{FAULT}}$  output is set HIGH-impedance. If the OCP circuit is active, setting the EN pin LOW returns the device to low-power mode.

### 8.6 Over-temperature protection (OTP)

If EN is set HIGH and the device temperature exceeds 125 °C, the device is in over temperature. The OTP circuit disables the N-channel MOSFET and sets the  $\overline{\text{FAULT}}$  output LOW. Transitions on the EN pin have no effect. Once its temperature decreases to below 115 °C the device returns to the defined state. The OTP circuit is disabled in low-power mode.

### 8.7 Reverse bias current/back drive protection (RCP)

The reverse bias current protection circuit can only be triggered when EN is set HIGH. If  $VBUS > (VINT + 30 \text{ mV})$  for longer than 4 ms; or  $VBUS > (VINT + 0.45 \text{ V})$  the device is in reverse bias. The RCP circuit disables the N-channel MOSFET and sets the  $\overline{\text{FAULT}}$  output LOW. Once  $VBUS < VINT$  for longer than 4 ms the device returns to the defined state. If the RCP circuit is active, setting the EN pin LOW returns the device to low-power mode.

### 8.8 $\overline{\text{FAULT}}$ output

The  $\overline{\text{FAULT}}$  output is an open-drain output that requires an external pull-up resistor. If any of the UVLO, OVLO, RCP, OCP or OTP circuits is activated, the  $\overline{\text{FAULT}}$  output is set LOW to indicate that a fault has occurred. The  $\overline{\text{FAULT}}$  output returns to the high impedance state automatically once the fault condition is removed.

### 8.9 VDET output

VDET is an analog output that allows a controller to monitor the voltage level on VBUS.

### 8.10 In-rush current protection

When the N-channel MOSFET is enabled, the in-rush current protection circuit clamps the switch current until  $VBUS = VINT - 200 \text{ mV}$ . The resistor connected to ILIM sets the clamp current. The in-rush current protection circuit is disabled in low-power mode.

## 9. Application diagram

The NX5P2090 typically connects a voltage source on VINT to the VBUS of a USB connector supporting USB3 OTG in a portable, battery operated device. The external resistor  $R_{ILIM}$  sets the maximum current limit threshold. The FAULT signal requires an additional external pull-up resistor which should be connected to a supply voltage matching the logic input pin supply level it is connected to.

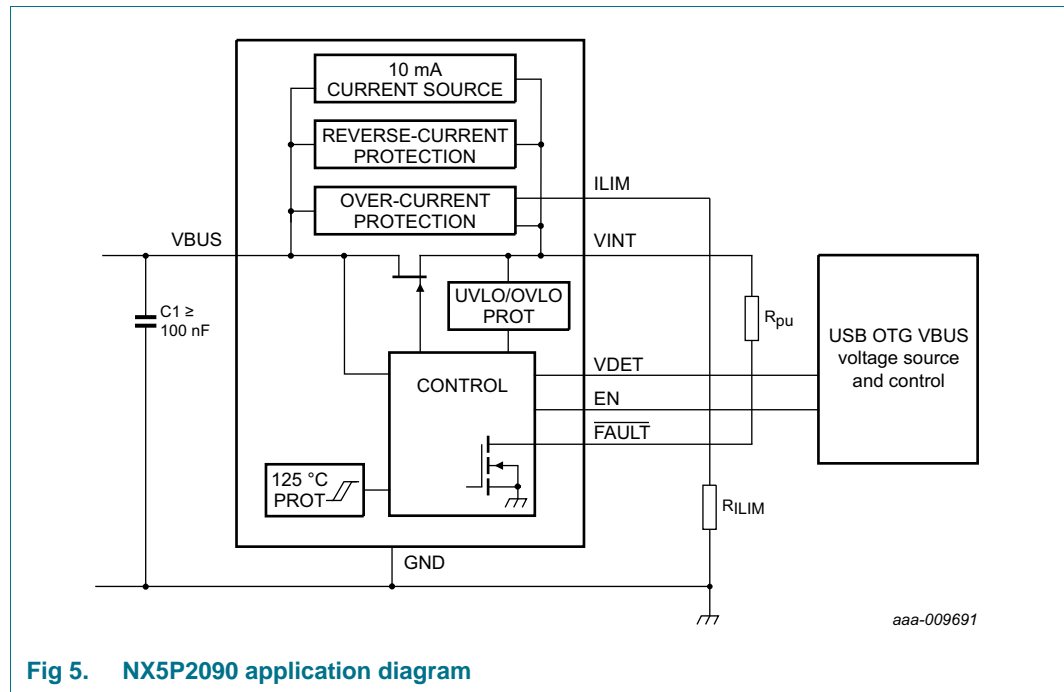


Fig 5. NX5P2090 application diagram

## 10. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_I$	input voltage	VBUS	[1] -0.5	+32	V
		VINT	[1] -0.5	+6.0	V
		EN, ILIM	[2] -0.5	VINT + 0.5	V
$V_O$	output voltage	FAULT	-0.5	+6.0	V
$I_{IK}$	input clamping current	EN: $V_I < -0.5 \text{ V}$	-50	-	mA
$I_{SK}$	switch clamping current	VBUS; VINT; $V_I < -0.5 \text{ V}$	-50	-	mA
$I_{SW}$	switch current	$T_{amb} = 85 \text{ °C}$	-	$\pm 2000$	mA
$T_{j(max)}$	maximum junction temperature		-40	+125	°C
$T_{stg}$	storage temperature		-65	+150	°C



**Table 6.** Limiting values ...continued

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$P_{\text{tot}}$	total power dissipation		[3] -	400	mW

- [1] The minimum and maximum switch voltage ratings may be exceeded if the switch clamping current rating is observed.  
 [2] The minimum input voltage rating may be exceeded if the input current rating is observed.  
 [3] The (absolute) maximum power dissipation depends on the junction temperature  $T_j$ . Higher power dissipation is allowed in conjunction with lower ambient temperatures. The conditions to determine the specified values are  $T_{\text{amb}} = 85\text{ °C}$  and the use of a two layer PCB.

## 11. Recommended operating conditions

**Table 7.** Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
$V_I$	input voltage	VINT	3.0	5.5	V
		EN, ILIM	0	VINT	V
$V_O$	output voltage	VBUS; EN = LOW	0	30	V
$T_{\text{amb}}$	ambient temperature		-40	+85	°C

## 12. Thermal characteristics

**Table 8.** Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient		[1] 82	K/W

- [1] The overall  $R_{\text{th(j-a)}}$  can vary depending on the board layout. To minimize the effective  $R_{\text{th(j-a)}}$ , all pins must have a solid connection to larger Cu layer areas e.g. to the power and ground layer. In multi-layer PCB applications, the second layer should be used to create a large heat spreader area right below the device. If this layer is either ground or power, it should be connected with several vias to the top layer connecting to the device ground or supply. Avoid using solder-stop varnish under the device.

### 13. Static characteristics

**Table 9. Static characteristics**
 $V_{I(VINT)} = 4.0\text{ V to }5.5\text{ V}$ ; unless otherwise specified; Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
V <sub>IH</sub>	HIGH-level input voltage	EN input	1.2	-	-	1.2	-	V
V <sub>IL</sub>	LOW-level input voltage	EN input	-	-	0.4	-	0.4	V
V <sub>O</sub>	output voltage	VDET; I <sub>VDET</sub> = -2 mA; 3 V < VBUS < 30 V	1.5	-	5.5	1.5	5.5	V
V <sub>OL</sub>	LOW-level output voltage	$\overline{\text{FAULT}}$ , I <sub>O</sub> = 8 mA	-	-	0.5	-	0.5	V
I <sub>O</sub>	output current	Current source	-	10	-	8	15	mA
		EN = HIGH; $\overline{\text{FAULT}}$ = Hi-Z	-	-	I <sub>ocp</sub>	-	I <sub>ocp</sub>	mA
I <sub>ocp</sub>	overcurrent protection current	EN = HIGH; see <a href="#">Figure 6</a>	-	-	-	-	-	mA
R <sub>pu</sub>	pull-up resistance	$\overline{\text{FAULT}}$	20	-	200	-	-	kΩ
V <sub>pu</sub>	pull-up voltage	$\overline{\text{FAULT}}$	-	-	VINT	-	VINT	V
R <sub>ILIM</sub>	current limit resistance	ILIM	20	-	300	20	300	kΩ
I <sub>GND</sub>	ground current	VBUS open; EN = LOW; see <a href="#">Figure 7</a> and <a href="#">Figure 8</a>	-	20	-	-	40	μA
		VBUS open; EN = HIGH; see <a href="#">Figure 7</a> and <a href="#">Figure 8</a>	-	220	-	-	360	μA
I <sub>OFF</sub>	power-off leakage current	VBUS = 0 V to 30 V; <a href="#">[2]</a> VINT = 0 V; see <a href="#">Figure 9</a>	-	2	-	-	20	μA
I <sub>S(OFF)</sub>	OFF-state leakage current	VBUS = 0 V to 30 V; <a href="#">[2]</a> see <a href="#">Figure 10</a> and <a href="#">Figure 11</a>	-	2	-	-	20	μA
V <sub>UVLO</sub>	undervoltage lockout voltage		3.0	3.2	3.4	3.0	3.4	V
V <sub>OVLO</sub>	overvoltage lockout voltage		5.5	5.9	6.25	5.5	6.25	V
V <sub>hys(OVLO)</sub>	overvoltage lockout hysteresis voltage		-	150	-	-	-	mV
C <sub>I</sub>	input capacitance	EN	-	2	-	-	-	pF
C <sub>S(ON)</sub>	ON-state capacitance		-	-	1	-	1	nF

[1] Typical values are measured at T<sub>amb</sub> = 25 °C and V<sub>I(VINT)</sub> = 5.0 V.

[2] Typical value is measured at T<sub>amb</sub> = 25 °C and V<sub>I(VBUS)</sub> = 5.0 V.

13.1 Graphs

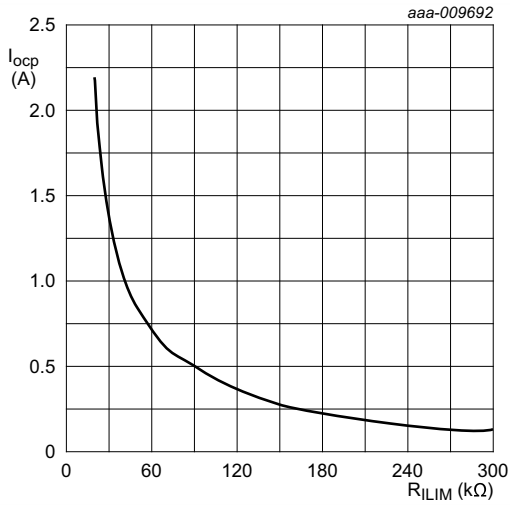
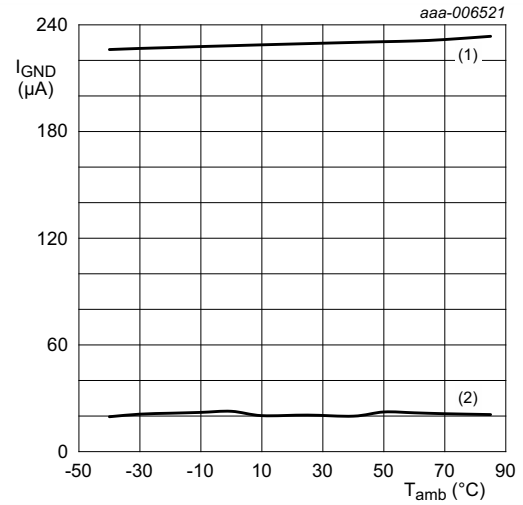


Fig 6. Typical overcurrent protection current and in-rush current limit versus the external resistor value.



- (1) Enabled
- (2) Disabled

Fig 7. Typical ground current versus temperature

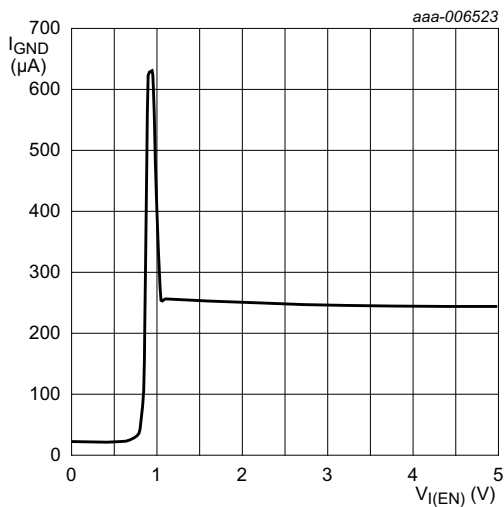
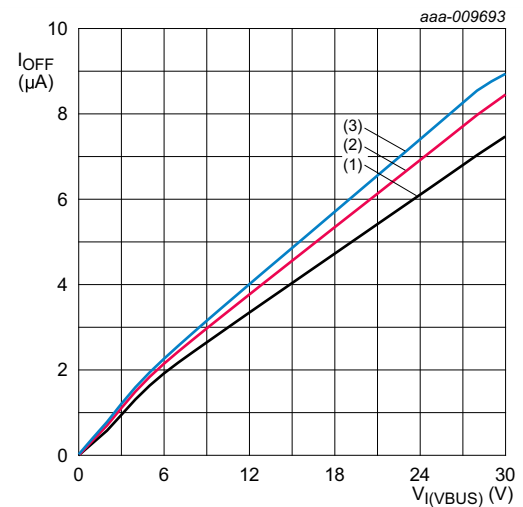
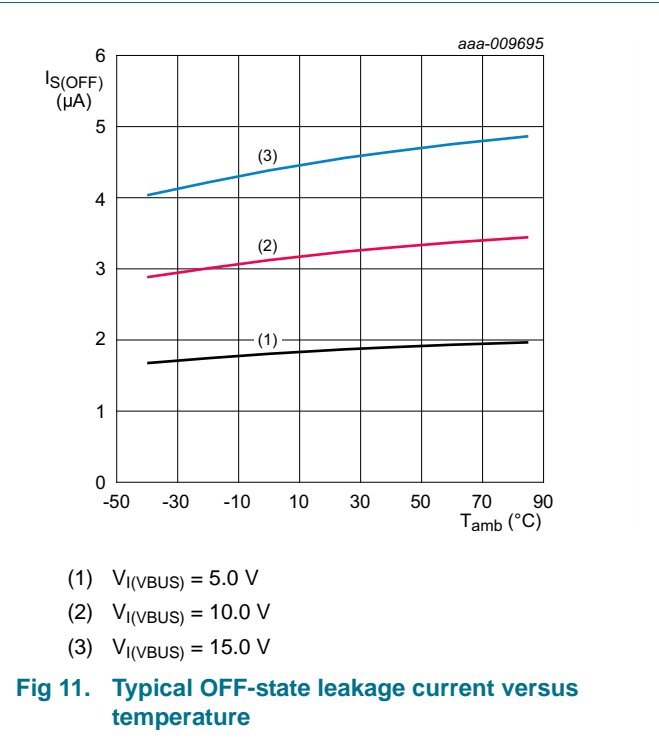
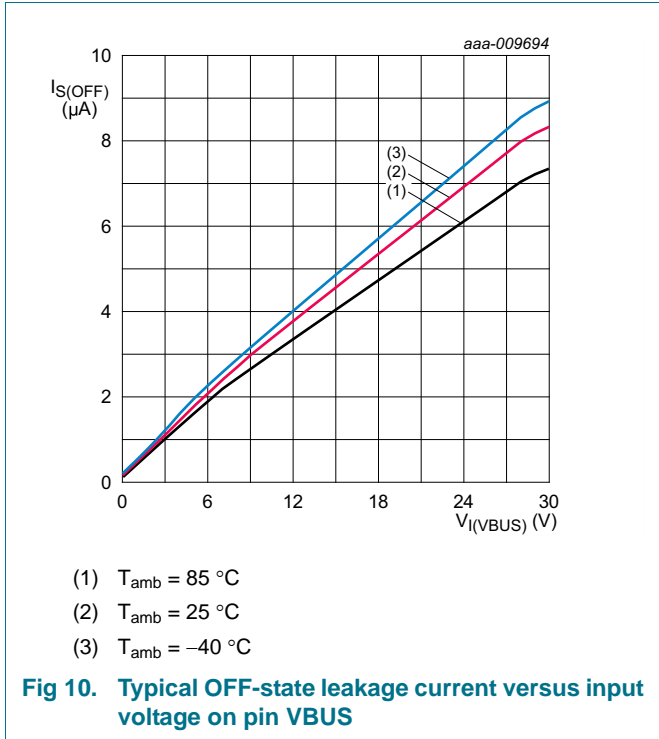


Fig 8. Typical ground current versus input voltage



- (1)  $T_{amb} = 85^{\circ}C$
- (2)  $T_{amb} = 25^{\circ}C$
- (3)  $T_{amb} = -40^{\circ}C$

Fig 9. Typical power-off leakage current versus input voltage on pin VBUS



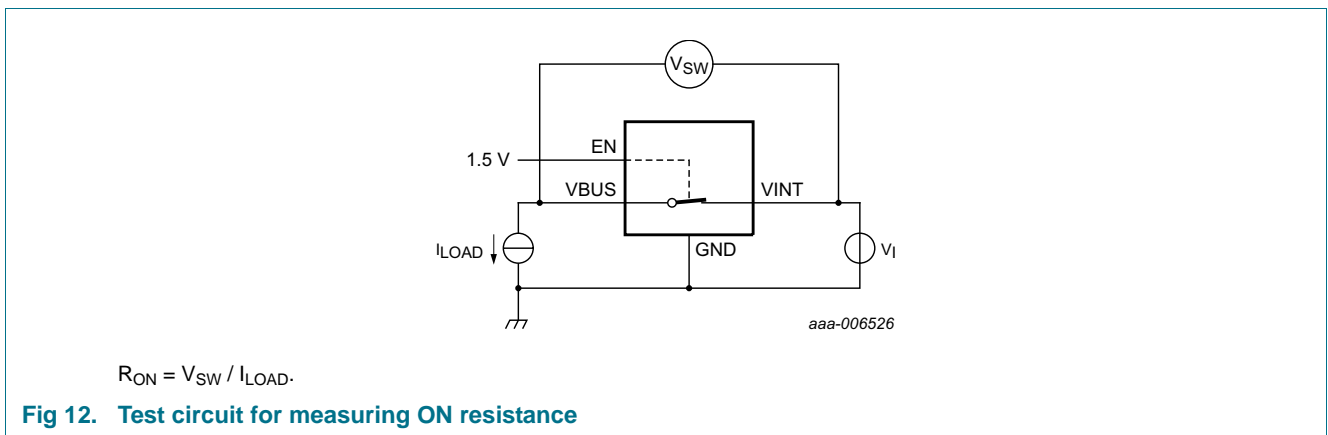
13.2 ON resistance

Table 10. ON resistance

At recommended operating conditions; voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	$T_{amb} = 25\text{ }^{\circ}\text{C}$			$T_{amb} = -40\text{ }^{\circ}\text{C to } +85\text{ }^{\circ}\text{C}$		Unit
			Min	Typ	Max	Min	Max	
$R_{ON}$	ON resistance	switch enabled; $I_{LOAD} = 200\text{ mA}$ ; see <a href="#">Figure 12</a> , <a href="#">Figure 13</a> and <a href="#">Figure 14</a> $V_{I(VINT)} = 4.0\text{ V to } 5.5\text{ V}$	-	60	-	-	100	m $\Omega$

13.3 ON resistance test circuit and waveforms



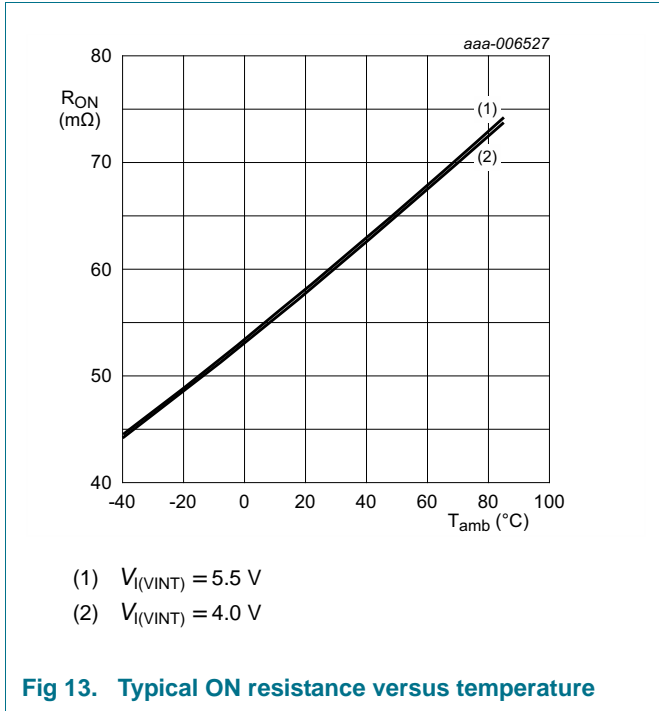


Fig 13. Typical ON resistance versus temperature

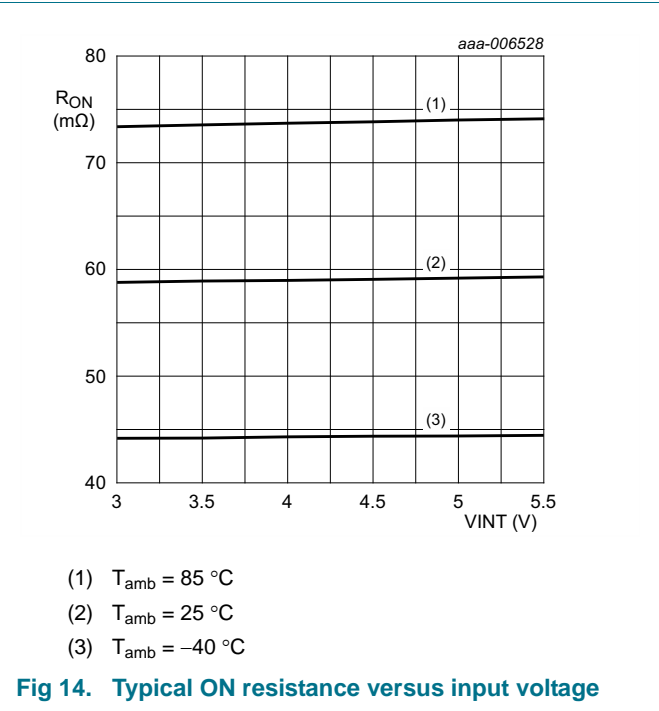


Fig 14. Typical ON resistance versus input voltage

## 14. Dynamic characteristics

Table 11. Dynamic characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V); for test circuit, see [Figure 16](#).  $V_{I(VINT)} = 4.0\text{ V to }5.5\text{ V}$ .

Symbol	Parameter	Conditions	$T_{amb} = 25\text{ °C}$			$T_{amb} = -40\text{ °C to }+85\text{ °C}$		Unit
			Min	Typ	Max	Min	Max	
$t_{en}$	enable time	EN to VBUS; see <a href="#">Figure 15</a>	-	0.24	-	0.16	-	ms
$t_{dis}$	disable time	EN to VBUS; see <a href="#">Figure 15</a>	-	1.5	-	-	-	ms
$t_{on}$	turn-on time	EN to VBUS; see <a href="#">Figure 15</a>	-	0.63	-	0.52	-	ms
$t_{off}$	turn-off time	EN to VBUS; see <a href="#">Figure 15</a>	-	34.5	-	-	-	ms
$t_{TLH}$	LOW to HIGH output transition time	VBUS; see <a href="#">Figure 15</a>	-	0.39	-	0.16	-	ms
$t_{THL}$	HIGH to LOW output transition time	VBUS; see <a href="#">Figure 15</a>	-	33	-	-	-	ms

14.1 Waveform and test circuits

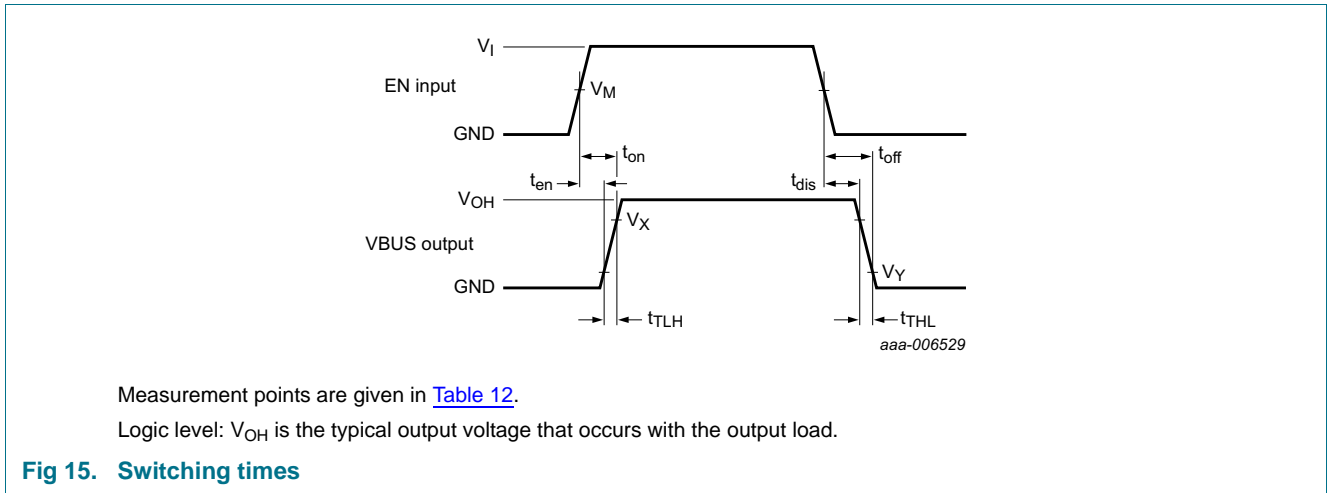


Table 12. Measurement points

Supply voltage	EN Input	Output	
$V_{I(VINT)}$	$V_M$	$V_X$	$V_Y$
4.0 V to 5.5 V	$0.5 \times V_I$	$0.9 \times V_{OH}$	$0.1 \times V_{OH}$

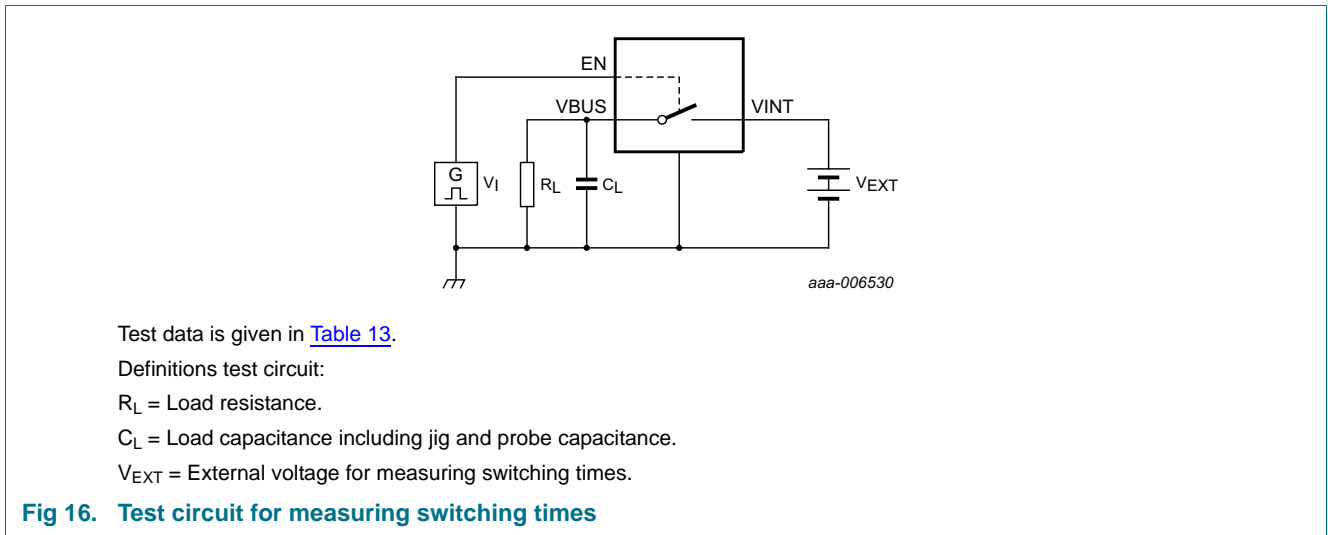
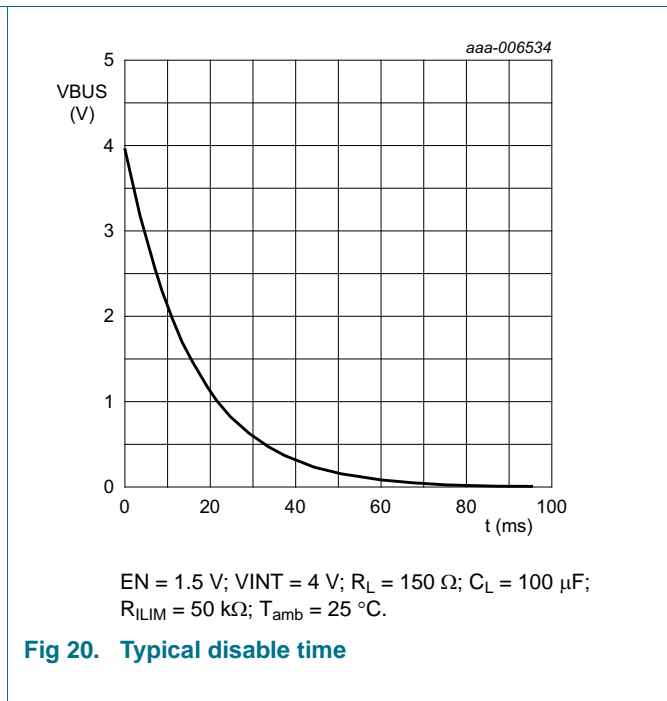
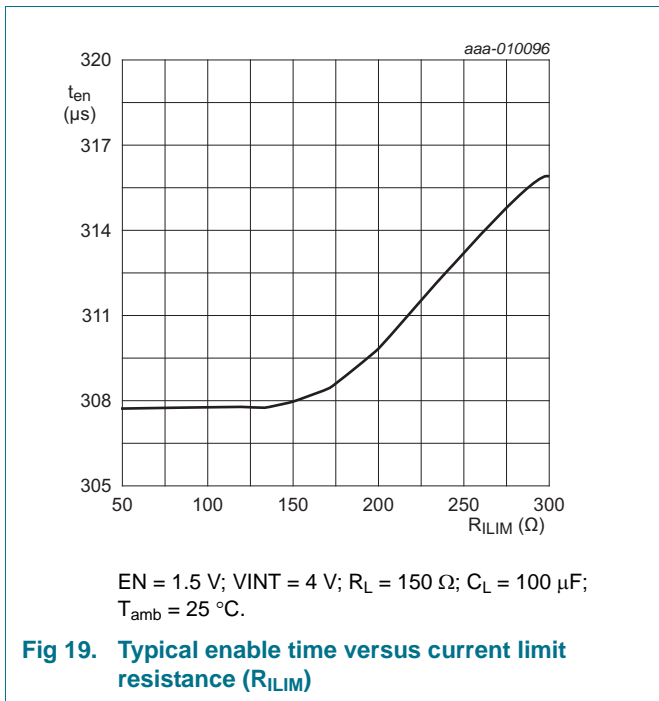
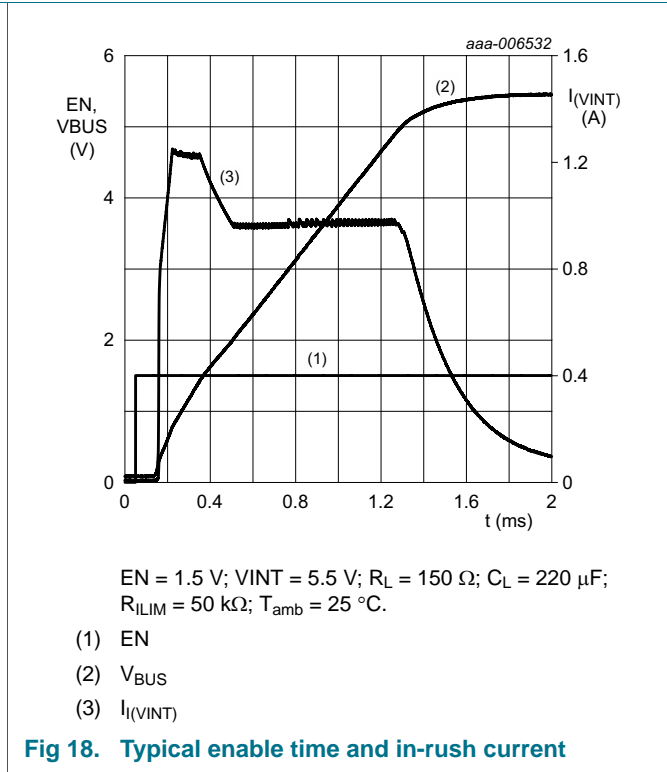
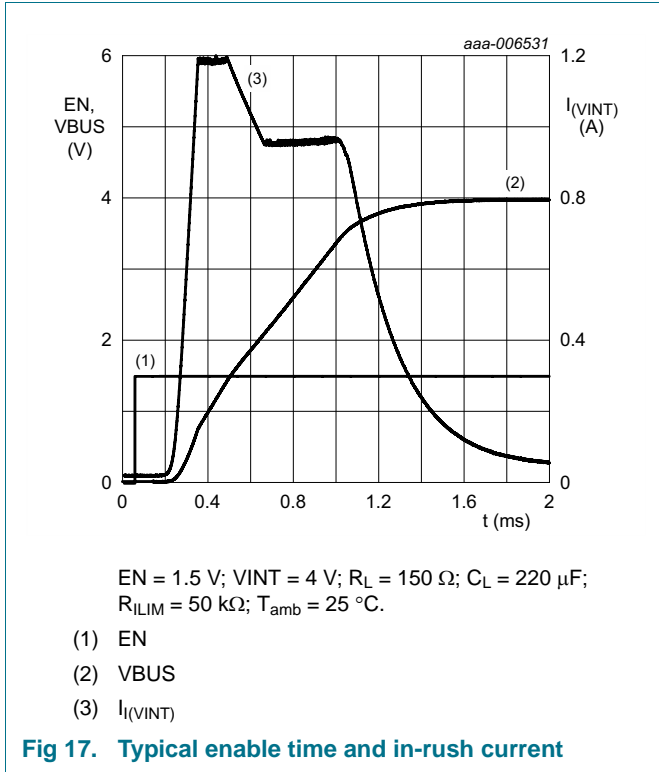
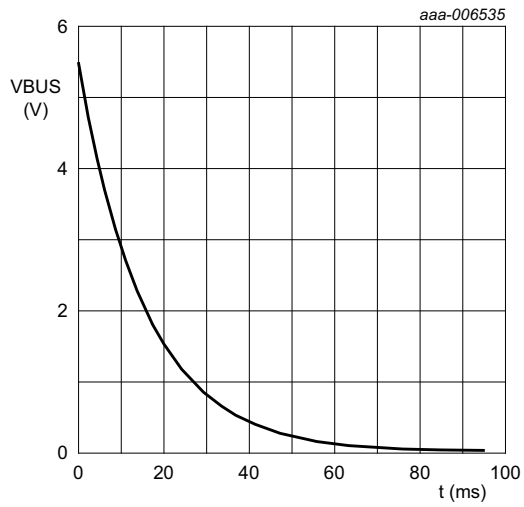


Table 13. Test data

Supply voltage	Input	Load	
$V_{EXT}$	$V_I$	$C_L$	$R_L$
4.0 V to 5.5 V	1.5 V	100 $\mu F$	150 $\Omega$





EN = 1.5 V; VINT = 5.5 V;  $R_L = 150 \Omega$ ;  $C_L = 100 \mu\text{F}$ ;  
 $R_{ILIM} = 50 \text{ k}\Omega$ ;  $T_{amb} = 25 \text{ }^\circ\text{C}$ .

Fig 21. Typical disable time

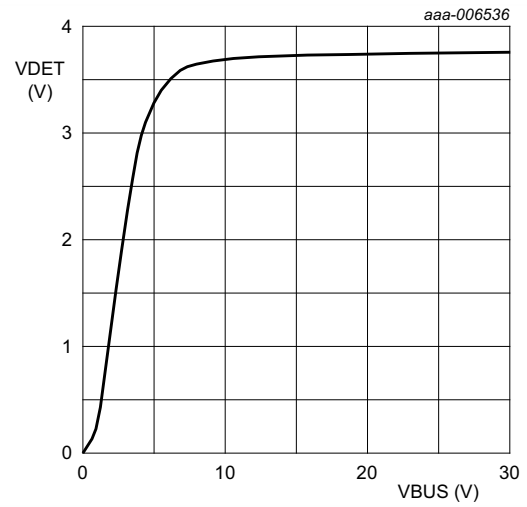


Fig 22. Typical VDET versus VBUS



15. Package outline

WLCSP9: wafer level chip-scale package;  
9 bumps; body 1.36 x 1.36 x 0.51 mm (Backside Coating included)

NX5P2090UK

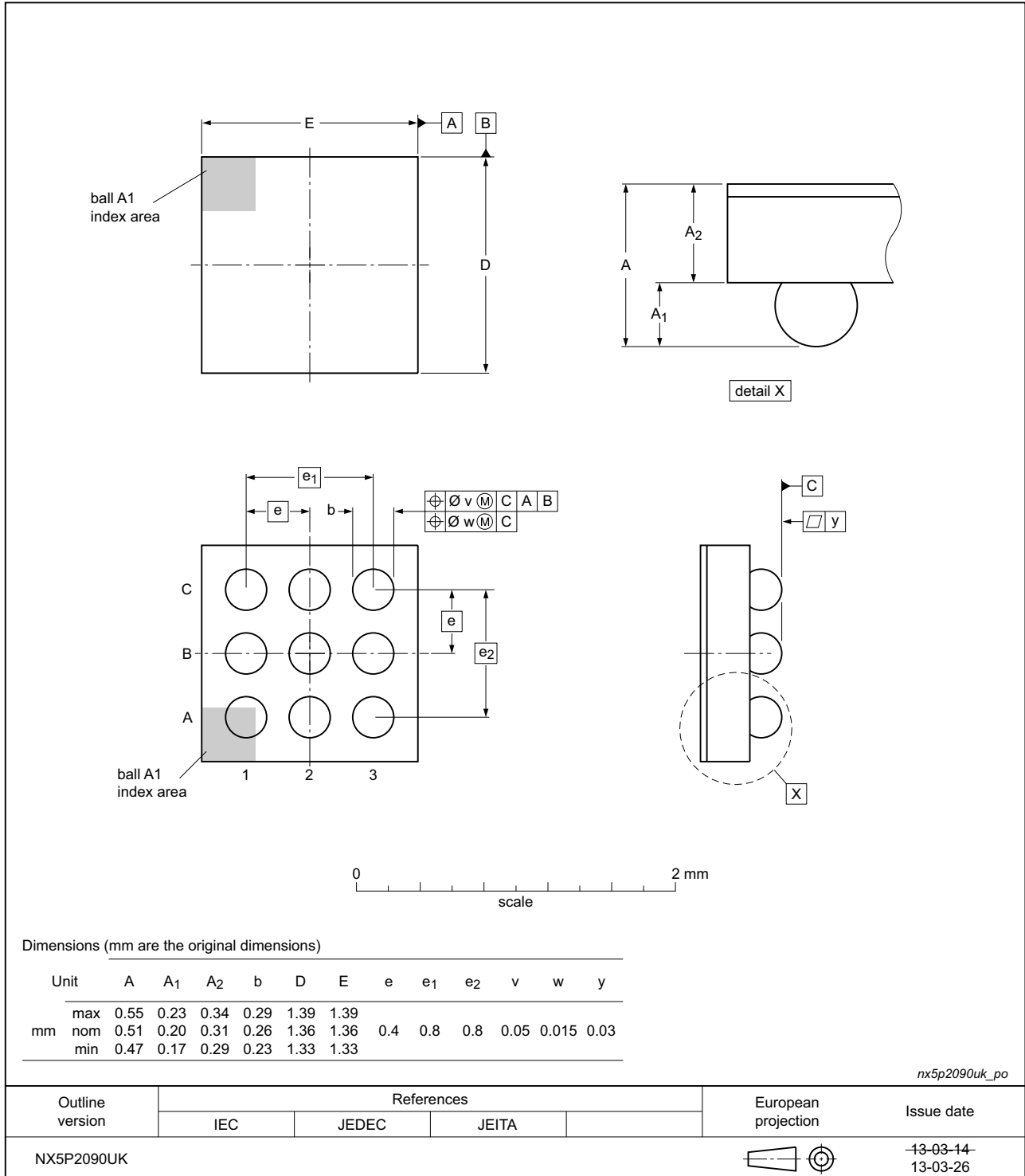


Fig 23. Package outline WLCSP9 package

## 16. Abbreviations

Table 14. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MOSFET	Metal-Oxide Semiconductor Field Effect Transistor
OCP	OverCurrent Protection
OTP	OverTemperature Protection
RCP	Reverse Current Protection
USB OTG	Universal Serial Bus On-The-Go
UVLO	Under-voltage lockout
VBUS	USB Power Supply
OVLO	Over-voltage lockout

## 17. Revision history

Table 15. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
NX5P2090 v.2	20131212	Product data sheet	-	NX5P2090 v.1
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## 18. Legal information

### 18.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

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